

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-6 (canceled)

7. (new) A method of manufacturing a semiconductor device comprising the steps of:

providing a lead frame having an upper surface, a lower surface, a frame portion, a plurality of leads which protrude inwardly in the frame portion, and a tub arranged in the frame portion;

providing a semiconductor chip having a main surface and a plurality of electrodes on the main surface;

fixing the semiconductor chip to an upper surface of the tub;

electrically connecting the electrodes of the semiconductor chip with the leads via a plurality of wires;

clamping the lead frame between a lower mold and an upper mold so as to form a first resin flow passage, a second resin flow passage, a first air vent passage and a cavity, the semiconductor chip and the wires being arranged in the cavity, the first resin flow passage being connected

with the cavity through the second resin flow passage, and the first air vent passage being connected with the cavity;

feeding molten resin into the cavity through the first resin flow passage and the second resin flow passage, and forming a resin body having a first portion cured in the first resin flow passage, a second portion cured in the second resin flow passage, a third portion cured in the cavity and fourth portion cured in the first air vent passage, wherein the semiconductor chip and connecting portions of the leads and the wires are sealed in the third portion of the resin body, and wherein lower surfaces of the leads are revealed from the resin body; and

cutting the second portion of the resin and the fourth portion of the resin by punching,

wherein the first resin flow passage is provided in a groove formed in the upper mold or the lower mold,

wherein the second portion of the resin body is formed inside a vertical space bounded by a side of a lead adjacent thereto, and

wherein the fourth portion of the resin body is formed inside a vertical space defined by a side of a lead adjacent thereto.

8. (new) A method of manufacturing a semiconductor device according to claim 7, wherein, in the step of clamping, a second air vent passage is formed in a groove of a parting face of the lower mold.

9. (new) A method of manufacturing a semiconductor device according to claim 7, including cutting the second portion of the resin and the fourth portion of the resin with leads.

10. (new) A method of manufacturing a semiconductor device according to claim 7, comprising a step of cutting the leads to separate them from the frame portion by punching.

11. (new) A method of manufacturing a semiconductor device according to claim 7, including in the step of cutting, cutting the second portion of the resin and the fourth portion of the resin by punching from the lower surface of the lead frame.

12. (new) A method of manufacturing a semiconductor device according to claim 7, including in the step of

clamping, forming the first resin flow passage on the frame portion.

13. (new) A method of manufacturing a semiconductor device according to claim 12, wherein the groove is spaced from an edge of the cavity.

14. (new) A method of manufacturing a semiconductor device according to claim 13, wherein the second resin flow passage is formed at a space between the groove and the cavity.

15. (new) A method of manufacturing a semiconductor device according to claim 7, further comprising a step of solder plating the lower surfaces of the leads before the step of cutting.